

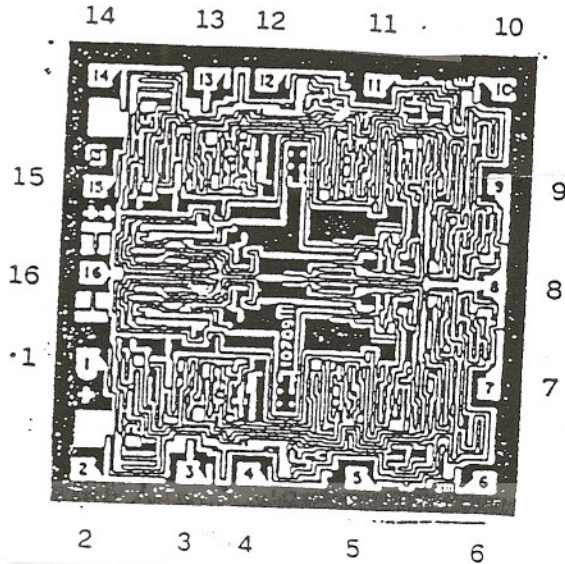


Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

<u>PAD NO</u>	<u>FUNCTIONS</u>
1	C _{X1}
2	R _X C _X (1)
3	RESET(1)
4	+TR(1)
5	-TR(1)
6	Q1
7	Q1
8	V _{SS}
9	Q2
10	Q2
11	-TR(2)
12	+TR(2)
13	RESET(2)
14	R _X C _X (2)
15	C _{X2}
16	V _{DD}



Top Material:
Backside Material:
Bond Pad Size:
Backside Potential:
Mask Ref:

APPROVED BY:MG

DIE SIZE :92 x 94

DATE: 10/28/08

MFG:RCA

THICKNESS:

P/N:CD4538 BH